

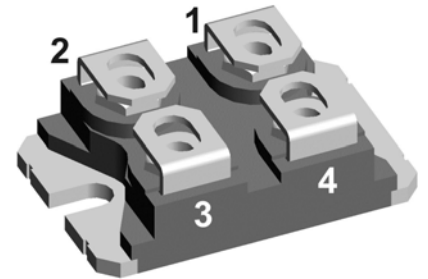
Standard Rectifier

3~ Rectifier	
V_{RRM}	= 1600 V
I_{DAV}	= 150 A
I_{FSM}	= 800 A


Half 3~ Bridge, Common Cathode

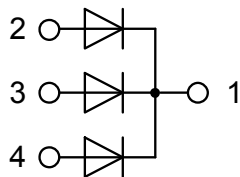
Part number

DMA150YC1600NA



Backside: isolated

 E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

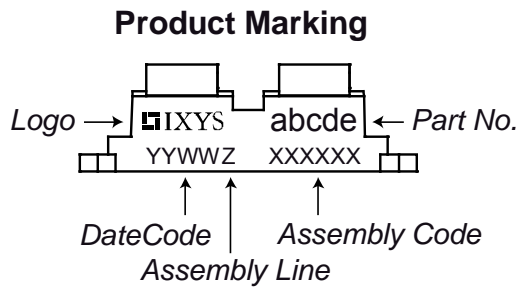
- Diode for main rectification
- For single and three phase bridge configurations

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper internally DCB isolated
- Advanced power cycling

Rectifier				Ratings				
Symbol	Definition	Conditions		min.	typ.	max.	Unit	
V_{RSM}	max. non-repetitive reverse blocking voltage					1700	V	
V_{RRM}	max. repetitive reverse blocking voltage					1600	V	
I_R	reverse current, drain current	$V_R = 1600$ V	$T_{VJ} = 25^\circ\text{C}$			100	μA	
		$V_R = 1600$ V	$T_{VJ} = 150^\circ\text{C}$			1.5	mA	
V_F	forward voltage drop	$I_F = 50$ A	$T_{VJ} = 25^\circ\text{C}$			1.21	V	
						1.68	V	
		$I_F = 150$ A	$T_{VJ} = 125^\circ\text{C}$			1.15	V	
						1.75	V	
I_{DAV}	bridge output current	$T_C = 95^\circ\text{C}$ rectangular $d = \frac{1}{3}$	$T_{VJ} = 150^\circ\text{C}$			150	A	
V_{FO}	threshold voltage	} for power loss calculation only				0.82	V	
r_F	slope resistance					6.3	m Ω	
R_{thJC}	thermal resistance junction to case					0.6	K/W	
R_{thCH}	thermal resistance case to heatsink				0.10		K/W	
P_{tot}	total power dissipation			$T_C = 25^\circ\text{C}$		165	W	
I_{FSM}	max. forward surge current	$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$			800	A	
						865	A	
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V	$T_{VJ} = 150^\circ\text{C}$			680	A
							735	A
I^2t	value for fusing	$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$			3.20	kA ² s	
						3.12	kA ² s	
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V	$T_{VJ} = 150^\circ\text{C}$			2.31	kA ² s
							2.25	kA ² s
C_J	junction capacitance	$V_R = 400$ V; $f = 1$ MHz	$T_{VJ} = 25^\circ\text{C}$		25		pF	

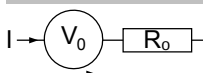
Package SOT-227B (minibloc)				Ratings		
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			150	A
T_{stg}	storage temperature		-40		150	°C
T_{vj}	virtual junction temperature		-40		150	°C
Weight				30		g
M_D	mounting torque		1.1		1.5	Nm
M_T	terminal torque		1.1		1.5	Nm
$d_{Spp/App}$	creepage distance on surface striking distance through air	terminal to terminal	10.5	3.2		mm
$d_{Spt/Abp}$		terminal to backside	8.6	6.8		mm
V_{ISOL}	isolation voltage	t = 1 second		3000		V
		t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	2500		V


Part number

- D = Diode
- M = Standard Rectifier
- A = (up to 1800V)
- 150 = Current Rating [A]
- YC = Half 3~ Bridge, Common Cathode
- 1600 = Reverse Voltage [V]
- NA = SOT-227B (minibloc)

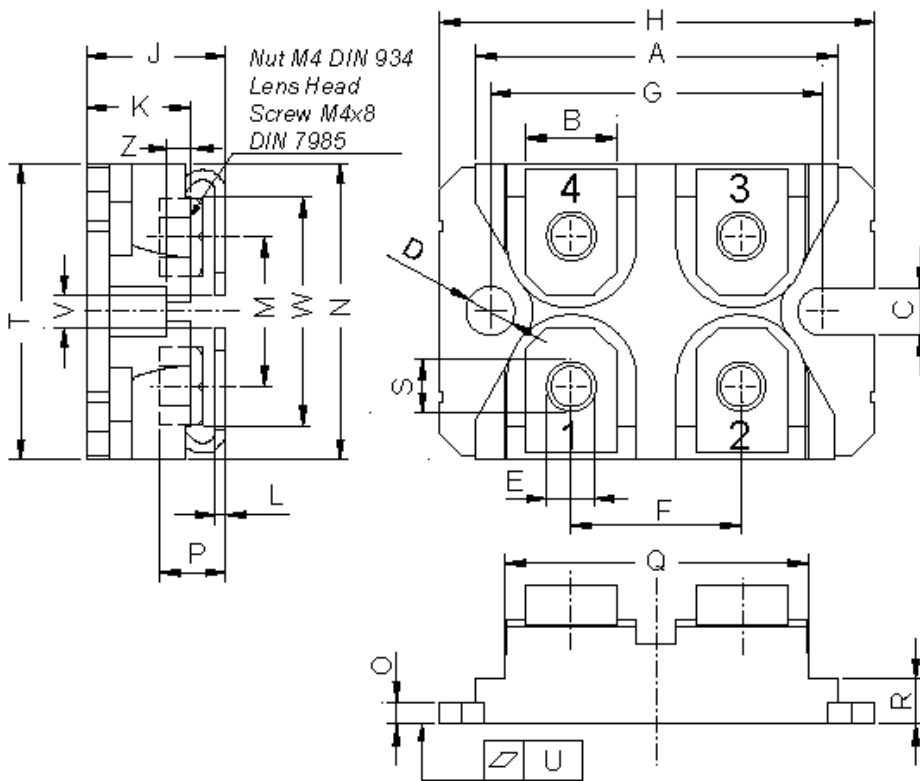
Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DMA150YC1600NA	DMA150YC1600NA	Tube	10	509174

Similar Part	Package	Voltage class
DMA150YA1600NA	SOT-227B (minibloc)	1600

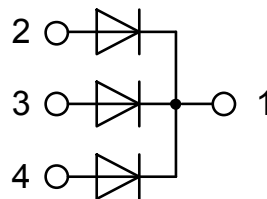
Equivalent Circuits for Simulation
** on die level*
 $T_{vj} = 150^\circ\text{C}$

Rectifier

$V_{0\ max}$	threshold voltage	0.82	V
$R_{0\ max}$	slope resistance *	4.4	mΩ

Outlines SOT-227B (minibloc)



Dim.	Millimeter		Inches	
	min	max	min	max
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
M	12.50	13.10	0.492	0.516
N	25.15	25.42	0.990	1.001
O	1.95	2.13	0.077	0.084
P	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
T	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Z	2.50	2.70	0.098	0.106



Rectifier

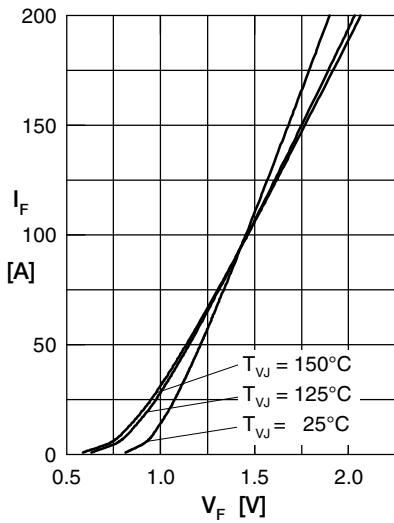


Fig. 1 Forward current versus voltage drop per diode

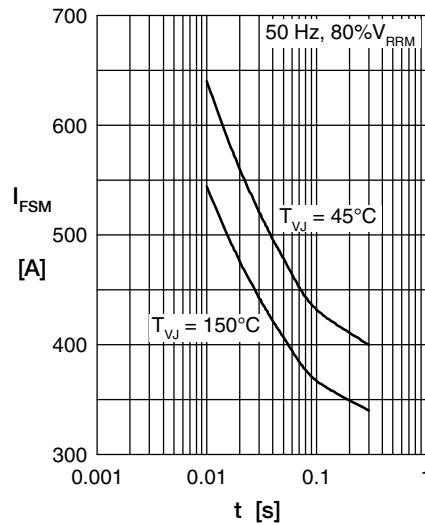


Fig. 2 Surge overload current

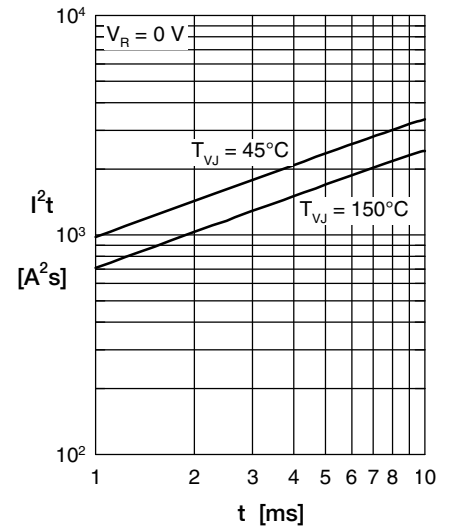


Fig. 3 I^2t versus time per diode

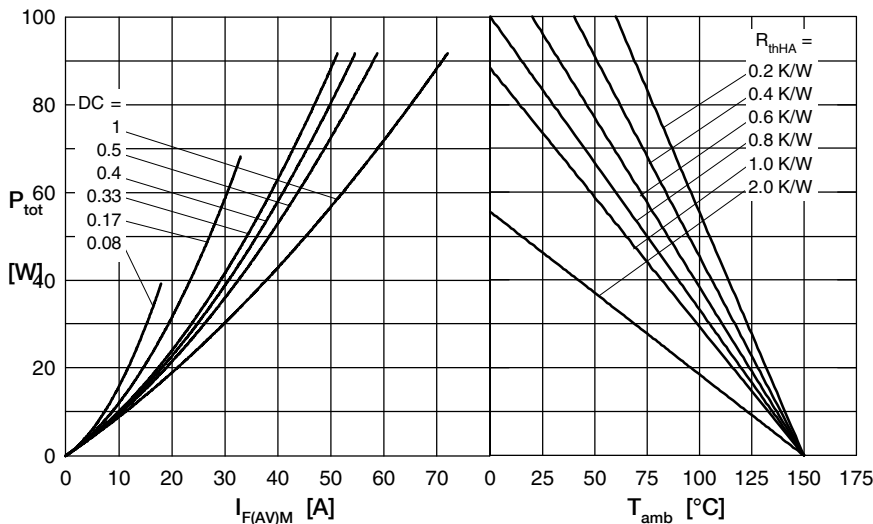


Fig. 4 Power dissipation versus direct output current and ambient temperature

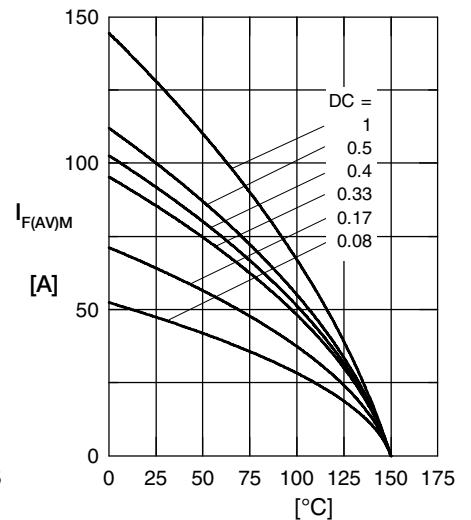


Fig. 5 Max. forward current versus case temperature

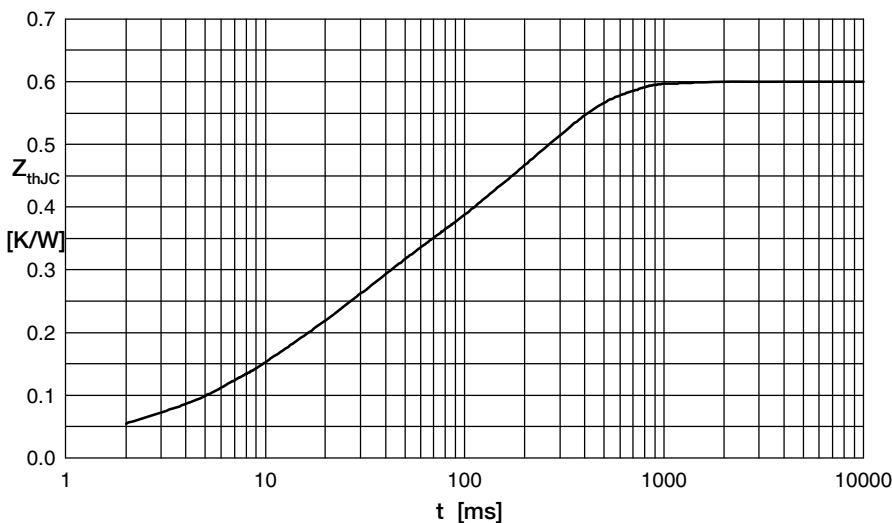


Fig. 6 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.017	0.01
2	0.013	0.00001
3	0.010	0.01
4	0.04	0.04
5	0.12	0.3